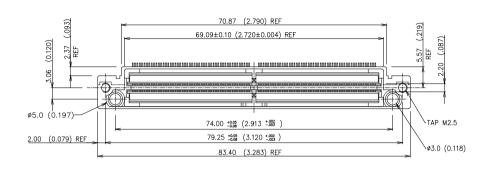
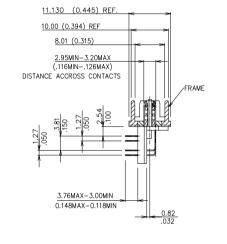
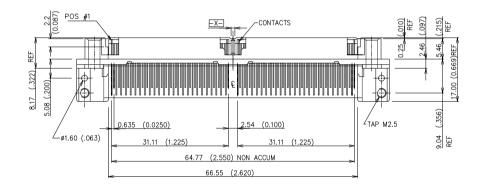
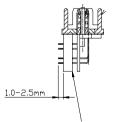
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PRODUCT NO.	SCREW
10013357-001/001LF	2 PCS 94148-001 NEEDED FOR EACH 10013357-001, PUT INTO PACKING BOX









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For application, move tail guide forward. Tail length is suggested to be in the range of 1.0~2.5mm

Note: Tail length is measured by gauge.

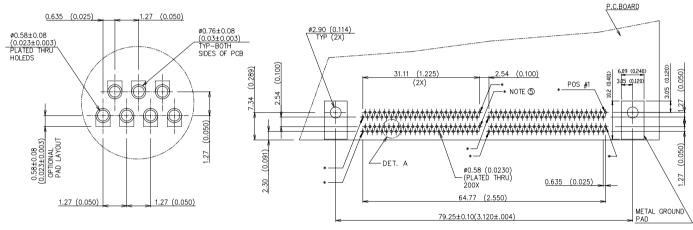
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PDM: Rev:C 3 STATUS: Released 222inted Sep 25, 2007

10013357-001/001LF

RECOMMENDED PC BOARD LAYOUT (FOR 2.4mm THK, PCB)



NOTE:

- 1.ALL BOARD HOLES ARE \$\overline{\Omega} 0.15/0.006 \overline{\Omega}\$
- 2.MATERIAL:
- -METAL FRAME : ZINC ALLOY#3
- -INSULATOR: HIGH TEMPERATURE ENGINEERING PLASTIC
- -CONTACT : BeCu -THK-.254 (.0100)

3.PLATING:

- -SOLDER TAILS : 150 μ "/3.81 μ SNPB
- -CONTACT PLATING : UNDERPLATING NICKEL 50 μ " OVERALL GXT IN CONTACT AREA 30 4"/.764
- 4.FRAME : 100 µm-in OVERALL COPPER.
- 5."*" REPRESENT LONG PIN AT FMLB FEATURE.
- 6. P/N WITH SUFFIX "LF" IS LEAD FREE P/N. SNPB PLATING IS CHANGED TO PURE TIN FOR LEAD FREE P/N
- 7. PACKING STANDARD GS-14-920 WILL BE APPLIED FOR LEAD FREE P/N'S
- 8. FOR LEAD FREE P/N'S, THE PRODUCT MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN
- 9. FOR LEAD FREE P/N'S, THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TERMERATURE FOR 40 SECONDS IN A CONVECTION, INFRO-RED OR VAPOR PHASE REFLOW OVEN.

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